ABSTRACT

SEMICONDUCTOR PACKAGE FOR A LARGE DIE

A semiconductor package and a method of assembly therefor are provided. A semiconductor package has a die pad and a plurality of bonding fingers. A spacer is attached to the die pad, and a large die is attached to the spacer. The large die is wire bonded to the plurality of bonding fingers using a plurality of bonding wires. The die pad, plurality of bonding fingers, spacer, large die, and bonding wires are encapsulated to form the semiconductor package. The semiconductor package can be either a single or dual row package, such as a QFN or BGA package. (Fig. 6)